

Nine Output 3.3V Buffer

Features

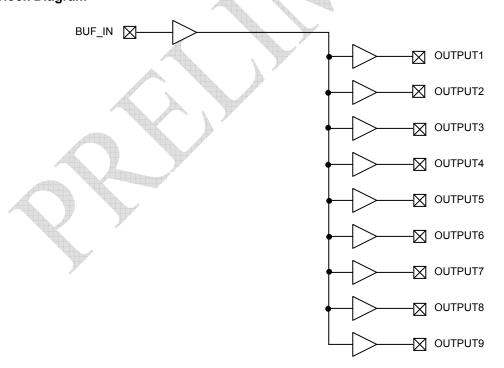
- One-input to Nine-Output Buffer/Driver
- Supports two DIMMs or four SO-DIMMs with one additional output for feedback to an external or chipset PLL
- Low power consumption for mobile applications
 Less than 32mA at 66.6MHz with unloaded outputs
- 1nS Input-Output delay
- Buffers all frequencies from DC to 133.33MHz
- Output-output skew less than 250pS
- Multiple V_{DD} and V_{SS} pins for noise and electromagnetic interference (EMI) reduction
- Space-saving 16 pin 150 mil SOIC Package
- 3.3V operation
- Commercial and Industrial temperature parts are available

Functional Description

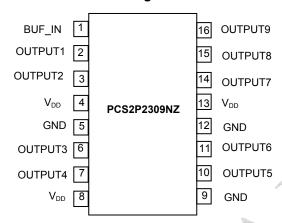
The PCS2P2309NZ is a low-cost buffer designed to distribute high-speed clocks in mobile PC systems and desktop PC systems with SDRAM support. The part has nine outputs, eight of which can be used to drive two DIMMs or four SO-DIMMs, and the remaining can be used for external feedback to a PLL. The device operates at 3.3V and outputs can run up to 133.33MHz.

The PCS2P2309NZ is designed for low EMI and power optimization. It has multiple V_{SS} and V_{DD} pins for noise optimization and consumes less than 32mA at 66.6MHz, making it ideal for the low-power requirements of mobile systems. It is available in an ultra-compact 150 mil 16 pin SOIC Package.

Block Diagram



Pin Configuration



Pin Description

Pin Signal		Description
4, 8, 13	V_{DD}	3.3V Digital Voltage Supply
5, 9, 12	GND	Ground
1	BUF_IN	Input Clock
2, 3, 6, 7, 10, 11, 14, 15, 16	OUTPUT [1:9]	Outputs



Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
VDD, V _{IN}	Voltage on any pin with respect to Ground	-0.5 to +4.6	V
T _{STG}	Storage temperature	-65 to +125	°C
T _A	Operating temperature	-40 to +85	°C
Ts	Max. Soldering Temperature (10 sec)	260	°C
TJ	Junction Temperature	150	°C
T_DV	Static Discharge Voltage (As per JEDEC STD22- A114-B)	2	KV
	stress ratings only and are not implied for functional use. Exposure to absolute maximum		8

Operating Conditions

Parameter	Description	Min	Max	Unit
V_{DD}	Supply Voltage	3.0	3.6	V
т	(Ambient Operating Temperature), Commercial	0	70	°C
T _A	(Ambient Operating Temperature), Industrial	-40	85	°C
C_L	Load Capacitance, Fout < 100MHz	-	30	pF
	Load Capacitance,100MHz < Fout < 133.33MHz	-	15	pF
C _{IN}	Input Capacitance	-	7	pF
BUF_IN, OUTPUT [1:9]	Operating Frequency	DC	133.33	MHz
t _{PU}	Power-up time for all V _{DD} 's to reach minimum specified voltage (power ramps must be monotonic)	0.05	50	mS



Electrical Characteristics for Commercial and Industrial Temperature Devices

Parameter	Description	Test Conditions	Min	Max	Unit
V_{IL}	Input LOW Voltage ¹		-	0.8	V
V _{IH}	Input HIGH Voltage ¹		2.0	-1	V
I₁∟	Input LOW Current	V _{IN} = 0V	-	50.0	μA
I _{IH}	Input HIGH Current	V _{IN} = V _{DD}	- 4	100.0	μA
V_{OL}	Output LOW Voltage ²	I _{OL} = 8 mA	-	0.4	V
V_{OH}	Output HIGH Voltage ²	I _{OH} = -8 mA	2.4	-	V
I_{DD}	Supply Current	Unloaded outputs at 66.66MHz	-	32	mA

Switching Characteristics for Commercial and Industrial Temperature Devices³

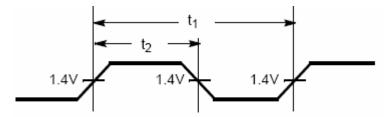
Parameter	Name	Description	Min	Тур	Max	Unit
t_D	Duty Cycle ² = t ₂ ÷t ₁	Measured at 1.4V	40.0	50.0	60.0	%
t ₃	Rise Time ²	Measured between 0.8V and 2.0V	-	-	1.50	nS
t ₄	Fall Time ²	Measured between 0.8V and 2.0V	7	-	1.50	nS
t ₅	Output to Output Skew ²	All outputs equally loaded	-	-	250	pS
t ₆	Propagation Delay, BUF_IN Rising Edge to OUTPUT Rising Edge ²	Measured at V _{DD} /2	1	5	9.2	nS

- Note:
 1. BUF_IN input has a threshold voltage of V_{DD}/2.
- 2. Parameter is guaranteed by design and characterization. It is not 100% tested in production.
- 3. All parameters specified with loaded outputs.

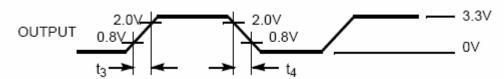


Switching Waveforms

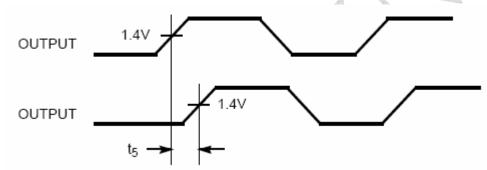
Duty Cycle Timing



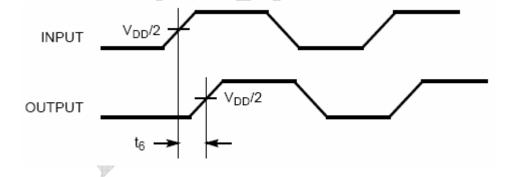
All Outputs Rise/Fall Time



Output-Output Skew

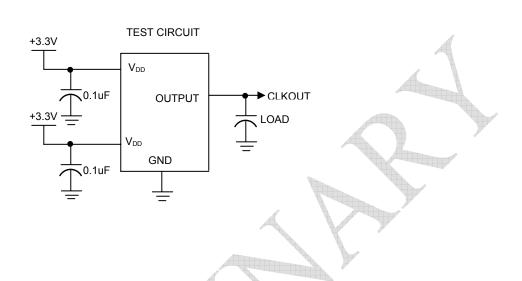


Input-Output Propagation Delay





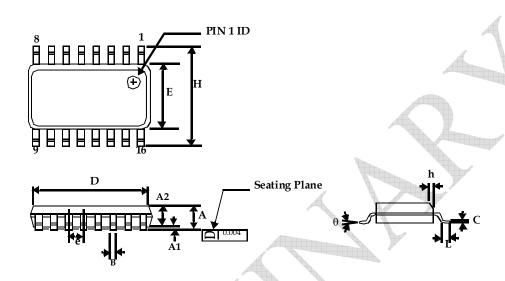
Test Circuits





Package Information

16-lead (150 Mil) Molded SOIC



	Dimensions				
Symbol	Inches		Millimeters		
	Min	Max	Min	Max	
Α	0.053	0.069	1.35	1.75	
A1	0.004	0.010	0.10	0.25	
A2	0.049	0.059	1.25	1.50	
В	0.013	0.022	0.33	0.53	
C	0.008	0.012	0.19	0.27	
D	0.386	0.394	9.80	10.01	
E	0.150	0.157	3.80	4.00	
е	0.050 BSC		1.27 BSC		
H	0.228	0.244	5.80	6.20	
h	0.010	0.016	0.25	0.41	
L	0.016	0.035	0.40	0.89	
θ	0°	8°	0°	8°	



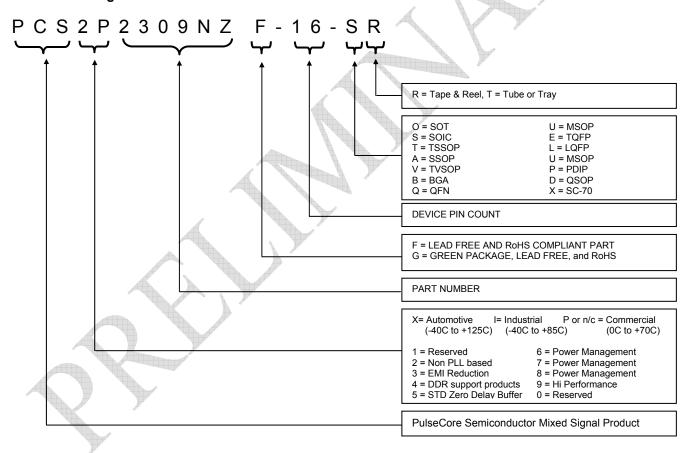




Ordering Codes

Part Number	Marking	Package Type	Temperature
PCS2P2309NZF-16-ST	2P2309NZF	16-pin 150-mil SOIC, Pb Free	Commercial
PCS2P2309NZF-16-SR	2P2309NZF	16-pin 150-mil SOIC, Tape and Reel, Pb Free	Commercial
PCS2I2309NZF-16-ST	2I2309NZF	16-pin 150-mil SOIC, Pb Free	Industrial
PCS2I2309NZF-16-SR	2I2309NZF	16-pin 150-mil SOIC, Tape and Reel, Pb Free	Industrial
PCS2P2309NZG-16-ST	2P2309NZG	16-pin 150-mil SOIC, Green	Commercial
PCS2P2309NZG-16-SR	2P2309NZG	16-pin 150-mil SOIC, Tape and Reel, Green	Commercial
PCS2I2309NZG-16-ST	2I2309NZG	16-pin 150-mil SOIC, Green	Industrial
PCS2I2309NZG-16-SR	212309NZG	16-pin 150-mil SOIC ,Tape and Reel, Green	Industrial

Device Ordering Information



Licensed under US patent #5,488,627, #6,646,463 and #5,631,920.





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Note: This product utilizes US Patent # 6,646,463 Impedance Emulator Patent issued to PulseCore Semiconductor, dated 11-11-2003

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